

Amendments to Specification:

Please substitute the following paragraph for the paragraph beginning on page 2, line 19 and ending on page 3, line 14:

~~FIG. 10 is~~ FIGS. 10(a) – 10(e) show a manufacturing process chart of a conventional IVH structured multilayer printed wiring board (refer to, for example, Japanese Laid-Open Patent Application (Kokai) (A) No. 2000-101248, or Japanese Laid-Open Patent Application (Kokai) (A) No. 2000-183528). In this process, ~~[[a)]~~ as seen in FIG. 10(a) first of all, a prepreg 1, in which an aramid nonwoven fabric is impregnated with epoxy resin, is drilled to form a predetermined number of holes for via holes 1a, and each of the holes for via holes 1a is filled with conductive paste or electrolytic plating 2. ~~[[b)]~~ Then, as seen in FIG. 10(b), the both sides of the prepreg 1 are overlapped with copper foils 3, 4 and heat pressed. Thereby, the epoxy resin of the prepreg 1 and the conductive paste or electrolytic plating 2 filled in the hole for via holes 1a come into contact with each other and integrate entirely; and thus, the copper foils 3, 4 on the both sides of the prepreg 1 are electrically connected via the conductive paste or electrolytic plating 2. ~~[[c)]~~ Then, as seen in FIG. 10(c), the copper foils 3, 4 are subjected to a patterning into a desired configuration. Thus, a hard double-sided substrate 9 is obtained including via holes 7 and 8 (hardened conductive paste or electrolytic plating 2) that electrically connect the conductive circuits 5 and 6 (patterned copper foils 3 and 4) on the both sides.

Please substitute the sentence on page 3, lines 15-20, with the following sentence:

When the double-sided substrate 9, which is formed as described above, is multilayered as a core layer into, for example, a 4 layered print wiring board,~~[[d)]~~ as seen

in FIG. 10(d), prepregs 11 filled with conductive paste or electrolytic plating 10 are positioned and built up in order on both sides of the double-sided substrate 9.

Please substitute the paragraphs beginning on page 7, line 17 and ending on page 8, line 16, with the following paragraphs:

~~FIG. 3 illustrates~~ FIGS. 3(a) – 3(e) illustrate a manufacturing process of double-sided substrates 22 (a first double-sided substrate 22 to a third double-sided substrate 22) (part 1);

~~FIG. 4 illustrates~~ FIGS. 4(a) – 4(e) illustrate a manufacturing process of the double-sided substrates 22 (the first double-sided substrate 22 to the third double-sided substrate 22) (part 2);

~~FIG. 5 illustrates~~ FIGS. 5(a) – 5(d) illustrate a manufacturing process of the double-sided substrates 22 (the first double-sided substrate 22 to the third double-sided substrate 22) which may be replaced with the process shown in FIG. 4(a) to FIG. 4 (d);

~~FIG. 6 illustrates~~ FIGS. 6(a) – 6(g) illustrate a manufacturing process of a junction substrate 23 (a first junction substrate 23, a second junction substrate 23);

~~FIG. 7 shows~~ FIGS. 7(a) – 7(c) show an example of a modification of an essential process of the multilayer printed wiring board manufactured by applying the concept of the present invention;

~~FIG. 8 shows~~ FIGS. 8(a) – 8(b) show another example of a modification of an essential process of the multilayer printed wiring board manufactured by applying the concept of the present invention;

~~FIG. 9 shows~~ FIGS. 9(a) – 9(b) show photographs of the surface of a columnar conductor 61a for comparing the surface before a roughening process (a) and after a roughening process (b);

~~FIG. 10 shows~~ FIGS. 10(a) – 10(e) show a manufacturing process of a conventional IVH structured as a multilayer printed wiring board; and

~~FIG. 11 shows~~ FIGS. 11(a) – 11(b) show problems in a conventional art.

Please substitute the paragraph on page 11, lines 17-20 with the following paragraph:

~~<Manufacturing process of the double-sided substrate 22>~~

~~FIG. 3 and FIG. 4~~ FIGS. 3(a) – 3(e) and FIGS. 4(a) – 4(e) are manufacturing process charts of the double-sided substrate 22 (the first double-sided substrate 22 to the third double-sided substrate 22).

Please substitute the paragraph on page 15, lines 9-13, with the following paragraph:

A process in FIG. 5(c): then, after peeling off the supporter 30, which becomes unnecessary due to the above-described transfer, on the bottom surface of the sheet-like insulation resin 33, the metal foil 35 for conductor circuits is pasted and heat pressed to integrate with each other (FIG. 5(d)).

Please substitute the section on page 15, lines 18-20, with the following section:

~~<Manufacturing process of the junction substrate 23>~~

Then, the manufacturing process of the junction substrate 23 will be described.

Please substitute the sentence on page 18, lines 12-13, with the following sentence:

~~FIG. 7 shows~~ FIGS. 7(a) – 7(c) show an essential process of an example of a modification.

Please substitute the section on page 19, lines 17-18, with the following section:

~~FIG. 8 shows~~ FIGS. 8(a) – 8(b) show an essential process of another example of the modification;

Please substitute the sentence on page 20, lines 14-16, with the following sentence:

~~FIG. 9 shows~~ FIGS. 9(a) – 9(b) show photographs of the surface of the columnar conductor 61a for comparing the states before the roughening process ~~[(a)]~~ (FIG. 9(a)) and after the roughening process ~~[(b)]~~ (FIG. 9(b)).